

LINQBOND DA-8060S

Silver Sintering Die Attach



- High thermal conductivity and adhesion to various leadframes
- Low Resin Bleed-Out (RBO)
- PFAS free

LINQBOND DA-8060S is a single-component, pressure-less silver sintering die attach adhesive, known for its exceptional adhesion, high thermal conductivity, and high reliability. It performs excellently with various leadframes types, including Ag-spot plated, bare copper, PPF, and ceramic. Additionally, **LINQBOND DA-8060S** boasts exceptional workability and low Resin bleed out properties, making it ideal for high-volume semiconductor packaging applications.

LINQBOND DA-8060S is typically used as die attach for high power applications such as 5G, EVs, Industrial, Consumer electronics, Telecommunications, Aerospace, Defense and semiconductor packages such as SIP, QFN, LGA and HBLED.

Cure Schedule

- Ramp to 130°C and hold for 30 min + ramp to 220°C and hold for 90 min
- Ramp rate 5°C/min

Uncured properties

Property	Value	Unit
Chemistry	Epoxy	–
Filler	Silver	-
Viscosity at 25 °C (5rpm)	12000	cps
Thixotropic index (0.5/5rpm)	5.8	-
Work life @25°C	24	hours

Cured properties

Property	Value	Unit
Volume Resistivity	9.95	μΩ.cm
Thermal Conductivity	120	W/m.K
Glass Transition Temperature (Tg)	165	°C
Coefficient of Thermal Expansion (CTE)	37	ppm
Modulus @ 25°C	8000	MPa
@200 °C	12000	
Die Shear Strength* @ 25°C	8.3	kg-f
@ 260°C	7.5	

* Based on 2mm x 2mm bare Si die on a bare Cu substrate using recommended cure condition.

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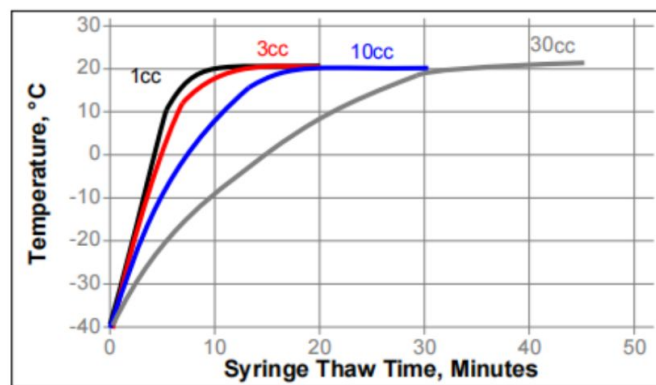
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- Ramp rate 5°C/min

These conditions serve as a reference only. Please establish the curing conditions based on the product's specific requirements.

Precautions:

1. When the material is taken out of refrigeration, thaw it first prior to use. Syringe should be placed vertically while thawing. Keep in an airtight container at room temperature.



2. The adhesive cannot be refrozen once exposed to room temperature.
3. Wear appropriate protective equipment and minimize direct contact with the human body. Refer to the Material Safety Data Sheet (SDS) before use.

Please note that the provided information is based on available data and typical conditions. For specific applications and detailed test results, refer to the actual test data and conduct appropriate certifications.

Storage and Handling

Store and transport in a -40°C Temperature. Keep away from fire and heat sources. It is strictly forbidden to store in outdoor environments.

- Shelf life at -40 °C is 365 days.

